

# **GBU8A - GBU8M** Bridge Rectifiers

### Features

- Glass passivated junction
- Surge overload rating: 200 amperes peak
- Reliable low cost construction utilizing molded plastic technique.
- Ideal for printed circuit board.



# Absolute Maximum Ratings \* $T_a = 25^{\circ}C$ unless otherwise noted

| Symbol             | Parameter   | Value       |     |     |            |     |     | Units |        |
|--------------------|---|-------------|-----|-----|------------|-----|-----|-------|--------|
|                    |   | 8A          | 8B  | 8D  | 8G         | 8J  | 8K  | 8M    | Units  |
| V <sub>RRM</sub>   | Maximum Repetitive Reverse Voltage  | 50          | 100 | 200 | 400        | 600 | 800 | 1000  | V      |
| V <sub>RMS</sub>   | Maximum RMS Bridge Input Voltage  | 35          | 70  | 140 | 280        | 420 | 560 | 700   | V      |
| V <sub>R</sub>     | DC Reverse Voltage (Rated V <sub>R</sub> )  | 50          | 100 | 200 | 400        | 600 | 800 | 1000  | V      |
| I <sub>F(AV)</sub> | Average Recitified Forward Current, @ $T_A = 100^{\circ}C$<br>@ $T_A = 45^{\circ}C$ |             |     |     | 8.0<br>6.0 |     |     |       | A<br>A |
| I <sub>FSM</sub>   | Non-Repetitive Peak Forward Surge Current<br>8.3ms Single Half-Sine-Wave            | 200         |     |     | А          |     |     |       |        |
| T <sub>STG</sub>   | Storage Temperature Range   | -55 to +150 |     |     | °C         |     |     |       |        |
| TJ                 | Operating Junction Temperature  | -55 to +150 |     | °C  |            |     |     |       |        |

\* These ratings are limiting values above which the serviceability of any semiconductor device may by impaired.

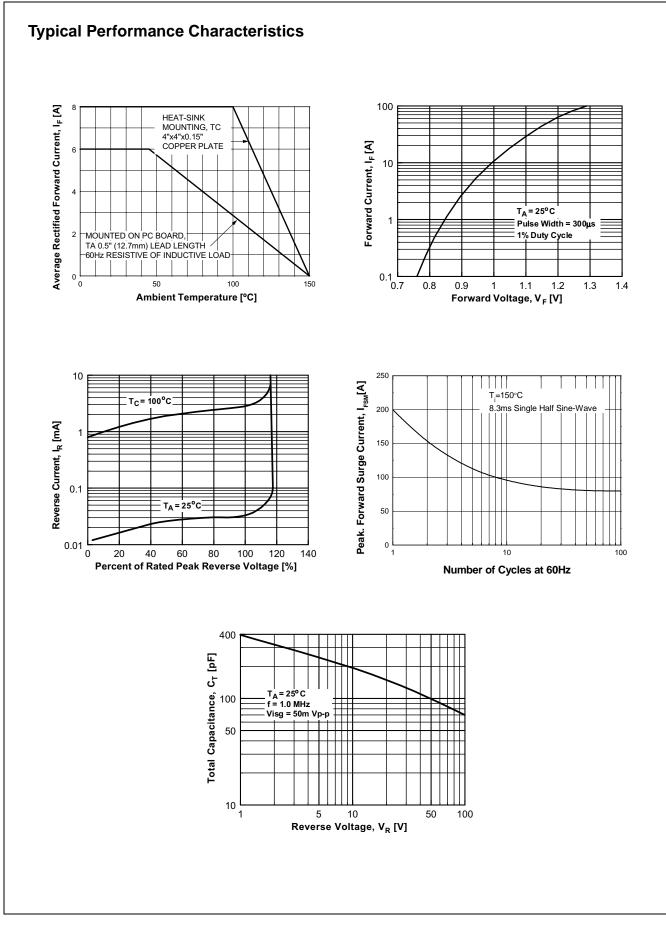
# **Thermal Characteristics**

| Symbol                | Parameter  | Value | Units |
|-----------------------|--|-------|-------|
| PD                    | Power Dissipation                                  | 16    | W     |
| $R_{	extsf{	heta}JA}$ | Thermal Resistance, Junction to Ambient, * per leg | 18    | °C/W  |
| $R_{	extsf{	heta}JC}$ | Thermal Resistance, Junction to Case, * per leg    | 3     | °C/W  |

\* Device mounted on PCB with  $0.5 \times 0.5"$  (12  $\times$  12mm).

# Electrical Characteristics T<sub>C</sub> = 25°C unless otherwise noted

| Symbol         | Parameter   | Value     | Units            |  |
|----------------|---|-----------|------------------|--|
| V <sub>F</sub> | Forward Voltage, per element @ 8.0A   | 1.0       | V                |  |
| I <sub>R</sub> | Reverse Current, per element @ Rated $V_R$<br>$T_A = 25^{\circ}C$<br>$T_A = 100^{\circ}C$ | 50<br>500 | μΑ<br>μΑ         |  |
|                | $I^{2}t$ Rating for Fusing t < 8.35ms   | 166       | A <sup>2</sup> s |  |



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|--------------------------|---------------------------|---|
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